

ABSTRACT

In a tape for semiconductor processing according to the present invention, a base material layer, a pressure-sensitive adhesive layer, and an adhesive layer having thermosetting properties are laminated in this order, and a contraction ratio of the adhesive layer is less than 2%, and a thermal elastic modulus of the adhesive layer is less than 5 MPa, after a curing treatment is performed at 130°C for 1 hour. Such a tape for semiconductor processing can be used as a dicing die bonding tape, and for example, can also be used as a tape for temporary fixing in a manufacturing procedure of a semiconductor device.